506575415 03/25/2021

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SHUN IKEURA	04/23/2019

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17279891

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DATE SIGNED:	03/25/2021	

Total Attachments: 1

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PATENT 506575415 REEL: 055719 FRAME: 0152

HP Inc. 3390 E. Harmony Road Mail Stop 35 Fort Collins, Colorado 80528

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RECORD ID:_ 85005497

ASSIGNMENT OF PATENT APPLICATION

I, the undersigned, for good and valuable consideration, the receipt of which is hereby acknowledged, agree to assign and transfer and hereby assign and transfer to HP PRINTING KOREA CO., LTD., having a principal business address of 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do, Korea, (hereinafter "HPPK"), its successors, and its assigns, my entire right, title, and interest, including all rights of priority, in, to, and under an application for patent entitled (English-language title in parentheses if said application for patent is in another language):

parentheses if said application for patent is in a	another language):		•	
画像形成システム (imaging system)				
Filing Date: October 17, 2018	Application No.:	2018-195673	a	Patent Office: JP
the subject matter, including any and all invent herein "patent" refers to any form of intellectual design rights, and utility model rights) (herein country or region or under any international as patent, any and all applications for patent dire said Inventions, any and all applications for indirectly claims priority or benefit, and any an of, divisional applications of, national-phase a application for patent for any of said Invention on or as a result of said Applications for Patent of said Applications for Patent or said Patents.	I property protection in nafter "Inventions"); a greement for any of se ctly or indirectly claimi patent from which an d all continuation appl pplications of, regions s) (hereinafter "Applic nt (hereinafter "Patent	ncluding, without ny and all exist ald Inventions (ir ing priority to or y application for ications of, cont al-phase applica ations for Paten	limitation, inventicing and future ap- icluding, without limited benefit of any approper any of inuation-in-part ap- itions of, renewals this any and all parts.	on rights, utility patent rights plications for patent of any mitation, said application fo disciplination for patent for any of a said Inventions directly o plications (hereinafter CIPs of, and substitutes for any tents which may be greater forths.
I HEREBY represent that I convey my fu entire right, title, and interest herein assigned a conflict herewith;	Ill rights in all countrie and transferred, and th	es and regions nat I have not ex	and under all inter ecuted and will no	national agreements to the it execute any agreement in
AND I HEREBY authorize HPPK, its s Applications for Patent in its name or in my authorize HPPK, its successors, its assigns, its and patent office of said application for patent,	name in any country nominees, and its led	or region or un ial representativ	der any internatio es to insert the filir	nal agreement, and further
AND I HEREBY authorize and request the duty it is to issue patents, to issue to HPPK, it Patents, in accordance with the terms of this as	ts successors, or its a	ssions, as assio	and under all inter nee of my entire r	national agreements whose ight, title, and interest, said
AND I HEREBY covenant and agree that such papers as may be necessary or desiral HPPK, its successors, or its assigns; communi all known facts respecting said Inventions, Apparent sign all lawful papers (including, withou applications) relating to said Inventions, Appli generally to do everything possible to aid HPP maintain, and enforce, for its or their own bene and Patents, provided the expenses which maits successors, its assigns, its nominees, or its	ble to perfect the title icate to HPPK, its succeptions for Patent, a timitation, divisiona cations for Patent, an K, its successors, its fit, proper intellectual p y be incurred by me in	in said Inventi- cessors, its assi- and Patents, tes I applications, of Id Patents; and assigns, its nom- property protection	ons, Applications gns, its nominees, tify in any legal or continuation applic make all rightful (inees, and its legat on for said toventic	for Patent, and Patents, to or its legal representatives, administrative proceedings cations, CIPs, and reissue paths and declarations and ai representatives to obtain, ons. Applications for Patent, ons. Applications
IN WITNESS WHEREOF, I hereunto set r	my hand and seal:			
Shuu Ikeura		23	4	2.49
Inventor's Signature		Day	Month	Year
Shun Ikeura Siven (First and Middle) Name(s) Family Name				
	•			

Rev 8/2018 (HPPK Assignment)

PATENT REEL: 055719 FRAME: 0153